





IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:

Yong-Jun Hu

Title:

LOW ANGLE, LOW ENERGY PHYSICAL VAPOR DEPOSITION OF ALLOYS

Docket No.: Filed:

303.098US4

April 5, 2001

Serial No.: 09/826,661

Due Date: January 26, 2002

Examiner:

Joseph Nguyen

Group Art Unit: 2815

Commissioner for Patents Washington, D.C. 20231

We are transmitting herewith the following attached items (as indicated with an "X"):

X A return postcard.

<u>X</u> An Amendment and Response under 37 CFR 1.111 (6 Pages).

X Clean Version of Pending Claims (5 pgs.).

Please consider this a PETITION FOR EXTENSION OF TIME for sufficient number of months to enter these papers and please charge any additional required fees or credit overpayment to Deposit Account No. 19-0743.

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

P.O. Box 2938, Minneapolis, MN 55402 (612-373-6900)

Reg. No. 24,916

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Commissioner for Patents, Washington, D.C. 20231, on this 24th day of January, 2002.

Name

Customer Number 21186

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

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(GENERAL)

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AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111

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Applicant has reviewed the Office Action mailed on October 26, 2001. Please amend the above-identified patent application as follows.

In the Claims

Please substitute the claim set in the appendix entitled Clean Version of Pending Claims for the previously pending claim set. The substitute claim set is intended to reflect cancellation of claim 38 and amendment of previously pending claims 31, 39, 43, 48, 55, 59, and 63-65. The specific amendments to individual claims are detailed in the following marked up set of claims.

- 31.(Amended) A contact hole for a semiconductor device, comprising:
 - a bottom surface of a first material;
 - at least one vertical sidewall of a second, insulating material;
- a generally planar layer of a third, conductive material covering only the bottom surface, the third material including at least two different constituent elements.
- 39.(Amended) A contact hole for a semiconductor device, comprising:
 - a bottom surface of a first material;
- at least one vertical sidewall of a second, insulating material and having a high aspect ratio;
- a generally planar layer of a third material covering only the bottom surface, the third material including at least two different constituent elements.